

VIRTUAL ASSEMBLY LINE INSIDE AN OPTISLANG SPM SYSTEM @BOSCH

F. LOERKE
D. KRÄTSCHMER
S. HAASE (CADFEM)
D. HAVERKAMP (CADFEM)
S. PETERS (CADFEM)

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Source: www.dynardo.de/en/library



Introduction

Electronic Control Units like ESP



**Electronic
Control Unit**



**Hydraulic
Unit**

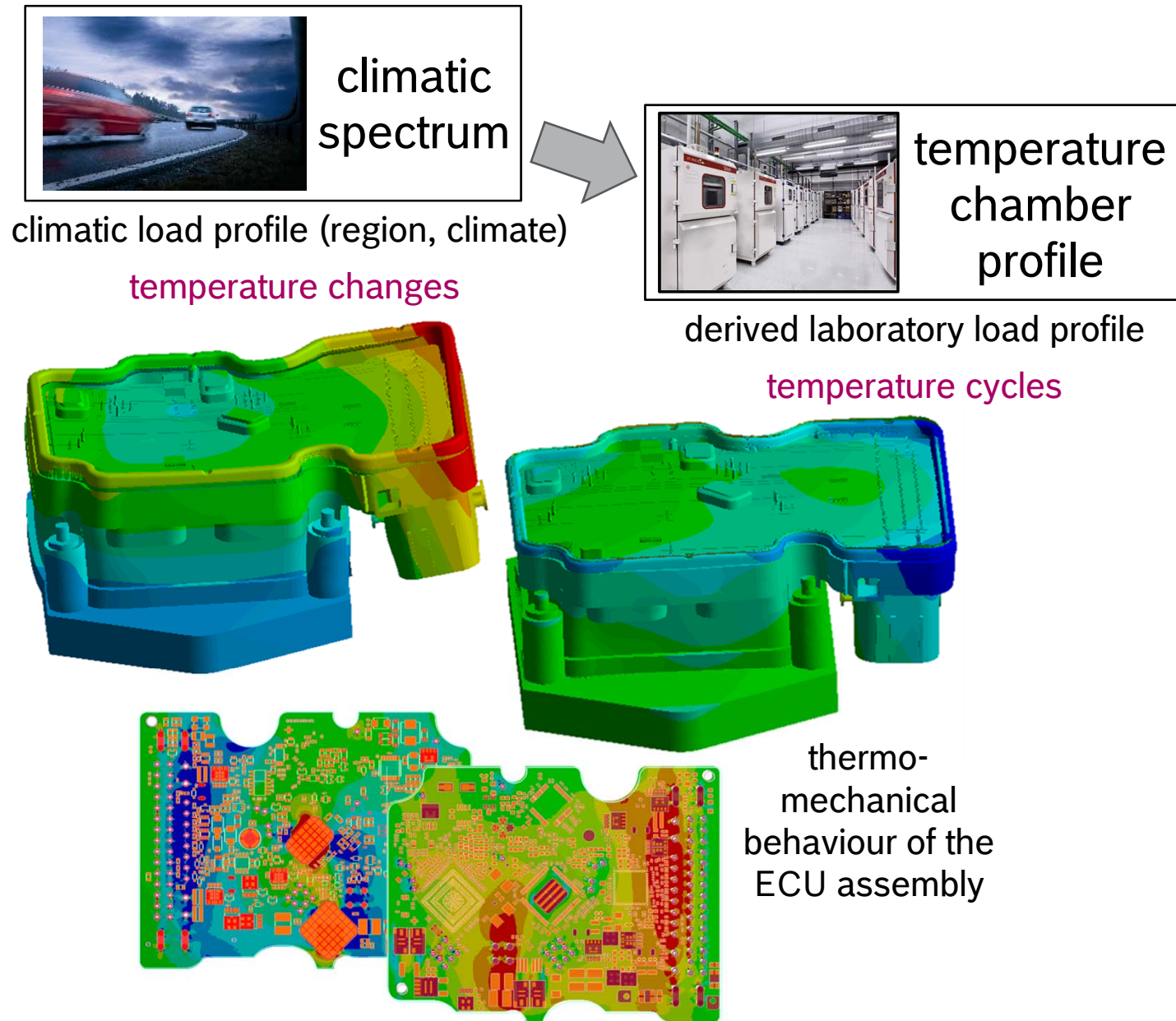


Motor



Efficient computational reliability assessment

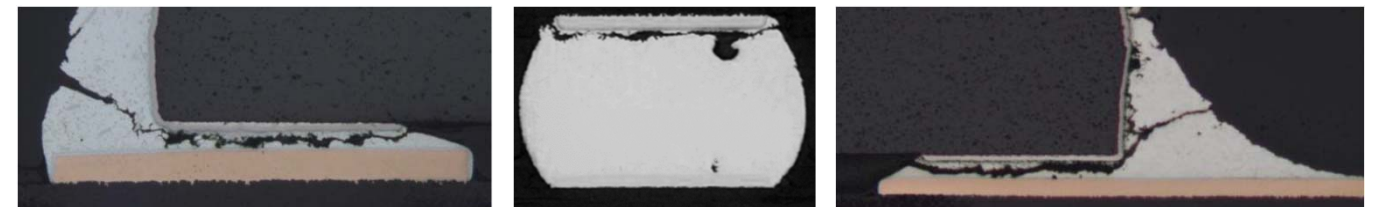
Automated, fast and reproducible



Solder joint reliability assessment to ensure functionality of electrical components

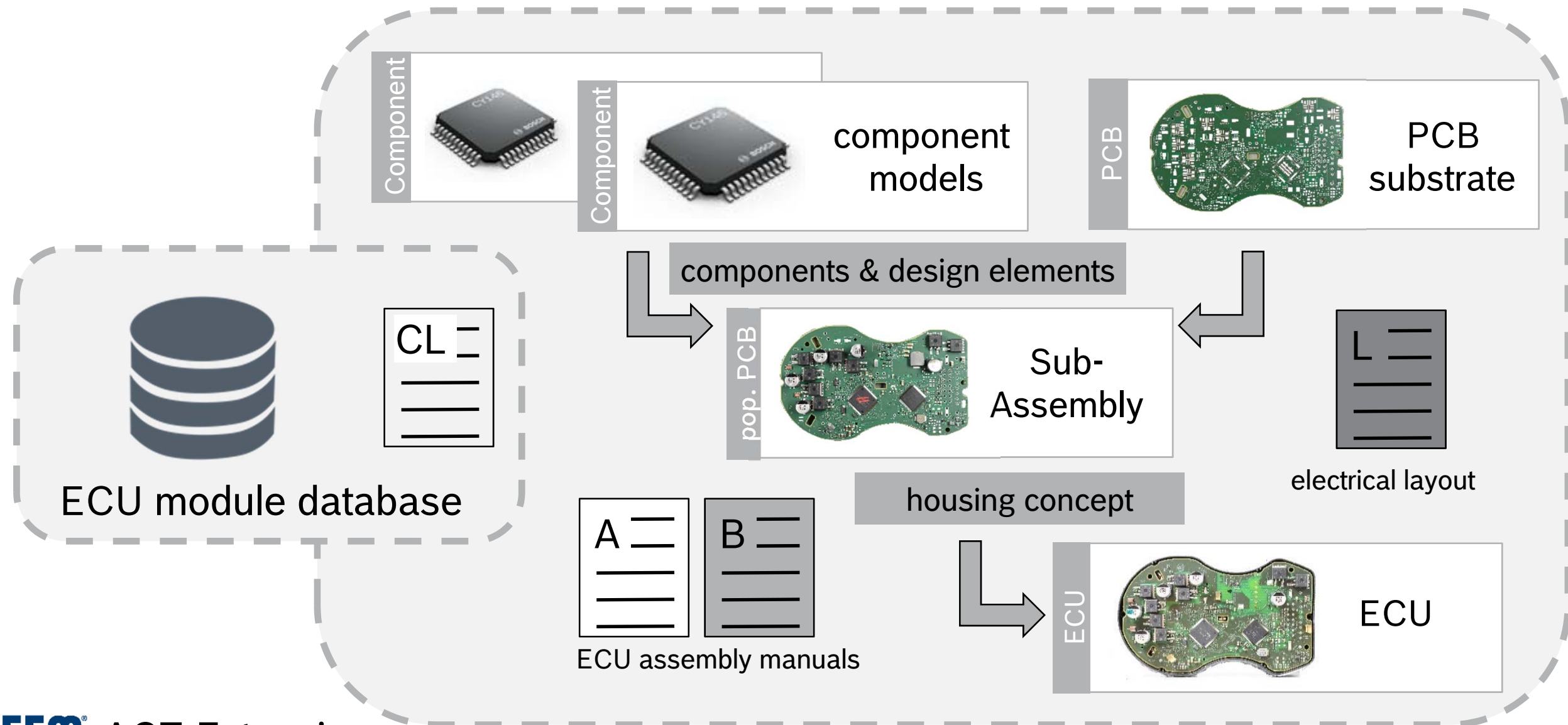
- **more than 600** components in an ESP layout!
- each component has **2 to 292** individual solder joints
- thousands of computational assessments of solder joint reliability w.r.t. creep fatigue

Computational assessment has to be fast and reproducible:
→ **automation!**



Virtual Assembly of ECUs

ACT solution



CADFEM ACT Extension

Virtual Assembly of ECUs

Web application



Virtual Assembly of ECUs

XML-based set-up

```
<?xml version="1.0" encoding="utf-8" ?>
<pcbClass>
  <pcb refDes="PCB" path="wbdata/03_pcb/pcb/ESP_Gen9_3_46pol_16SH1221H000000008.wbpz" pcbThickness="1.678" componentContactReference="contact_PCB" housingContactReference="contact_ECU">
    <transformation x="0.0" y="0.0" z="0.0" unit="mm" />
    <rotation xy="0.0" yz="0.0" zx="0.0" unit="degree" />
    <transformationPopPcb x="0.0" y="0.0" z="0.0" unit="mm" />
    <rotationPopPcb xy="0.0" yz="0.0" zx="0.0" unit="degree" />
  </pcb>
  <filters>
    <filter name="Physics" value="Thermal" />
    <filter name="Stackup" value="16SH1221H000000008" />
    <filter name="Product" value="ESP_Gen9_3" />
    <filter name="Connector" value="46pol" />
  </filters>
</pcbClass>

<?xml version="1.0" encoding="utf-8" ?>
<ecadClass>
  <ecad name="1030L05925_v01" path="wbdata/03_pcb/ecad/16SH1221H000000008_1030L05925_v01.anf" author="krd1ku" version="1.0" date="2018-11-13">
    <transformation x="0" y="0" z="-0.8" unit="mm" />
  </ecad>
  <ecadGeometry stringID="PCB(PCB)" />
  <ecadSettings advancedModeling="black/white" tracematConductive="ECAD_Cu" tracematDielectric="ECAD_FR4" platingThickness="0.025" unit="mm" platingMaterial="ECAD_Cu" />
  <ecadTileSize x="24" y="18" boundX="0.64" boundY="0.64" />
  <filters>
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    <filter name="Product" value="ESP_Gen9_3" />
    <filter name="Connector" value="46pol" />
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  </filters>
</ecadClass>

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<cpReportClass>
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  <filters>
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    <linkedFile path="ecad/16SH1221H000000008_1030L05925_v01.xml" />
    <linkedFile path="cpreport/CPR_1030L05925_v01.xml" />
  </linkedFiles>
</linkedFilesClass>
```

XMLs

- ▶ Example: PCB
- ▶ Predefinition of possible configurations

Virtual Assembly of ECUs

Domain based filtering

Filter

Prepare PCB

Populate PCB

Assembly

Physics

Solve

Postprocessing

dDOE

pDOE

Workflow

Run

Filter

Baseline

ESP_Gen9_3

Analysis

Transient_Thermal_SI_m

analysis - Transient_Thermal_SI_m

XML Details

Element	Value
analysis.analysisSystem	Transient Thermal
analysis.unitSystem	m

Filters

Name	Value
Physics	Thermal

- Filtering
- ▶ filtering of product classes and physical domains
 - ▶ users are only provided with options valid for their product class

Virtual Assembly of ECUs

PCB preparation

Filter

Prepare PCB

Populate PCB

Assembly

Physics

Solve

Postprocessing

dDOE

pDOE

Workflow

Run

user1

Logout

i

?

Prepare PCB

PCB

ESP_Gen9_3_EV7110_B1

^

Components

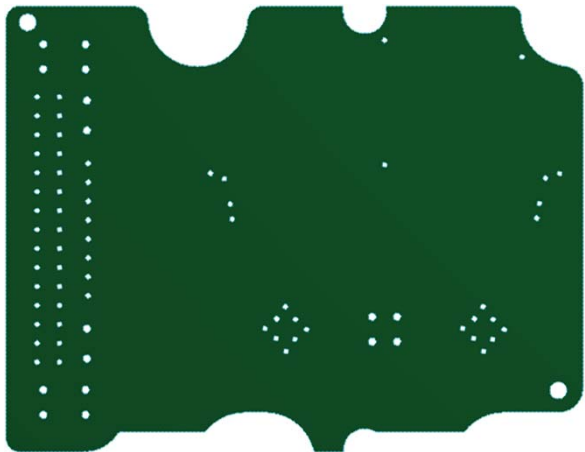
XML Details

Element	Value
analysis.analysisSystem	Transient Thermal
analysis.unitSystem	m

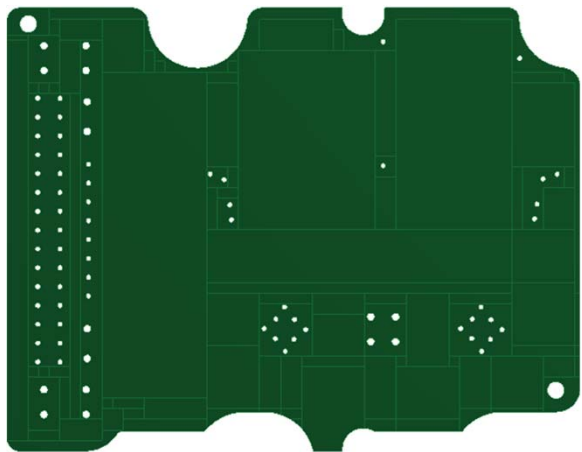
Filters

Name	Value
Physics	Thermal

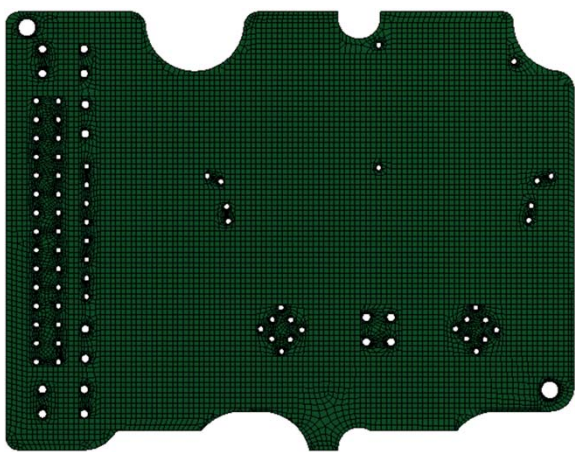
CAD import



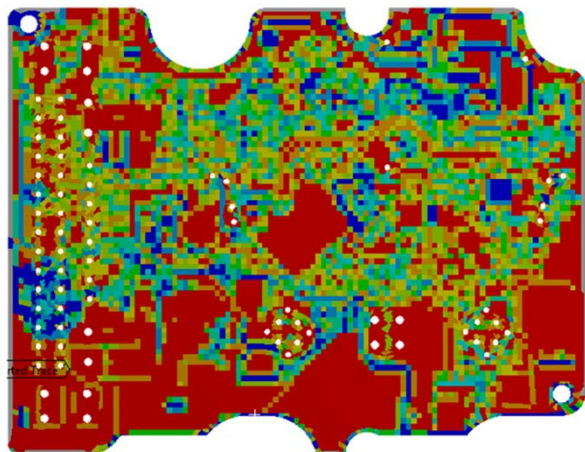
Slicing



Meshing



Circuit layout mapping



Virtual Assembly of ECUs

PCB population



user1
Logout  

Filter

Prepare PCB

Populate PCB

Assembly

Physics

Solve

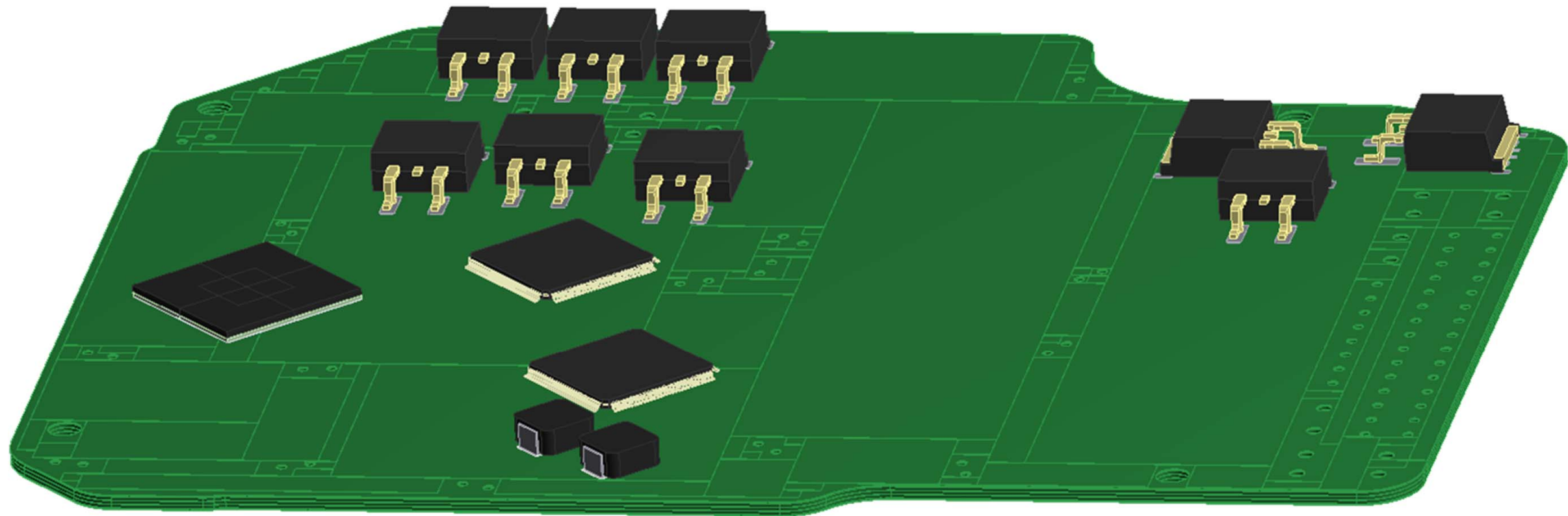
Postprocessing

dDOE

pDOE

Workflow

Run



PCB population

- ▶ Matching of domain-relevant components with electric layout
- ▶ Automated component placement

Virtual Assembly of ECUs

ECU assembly



user1
Logout

Filter

Prepare PCB

Populate PCB

Assembly

Physics

Solve

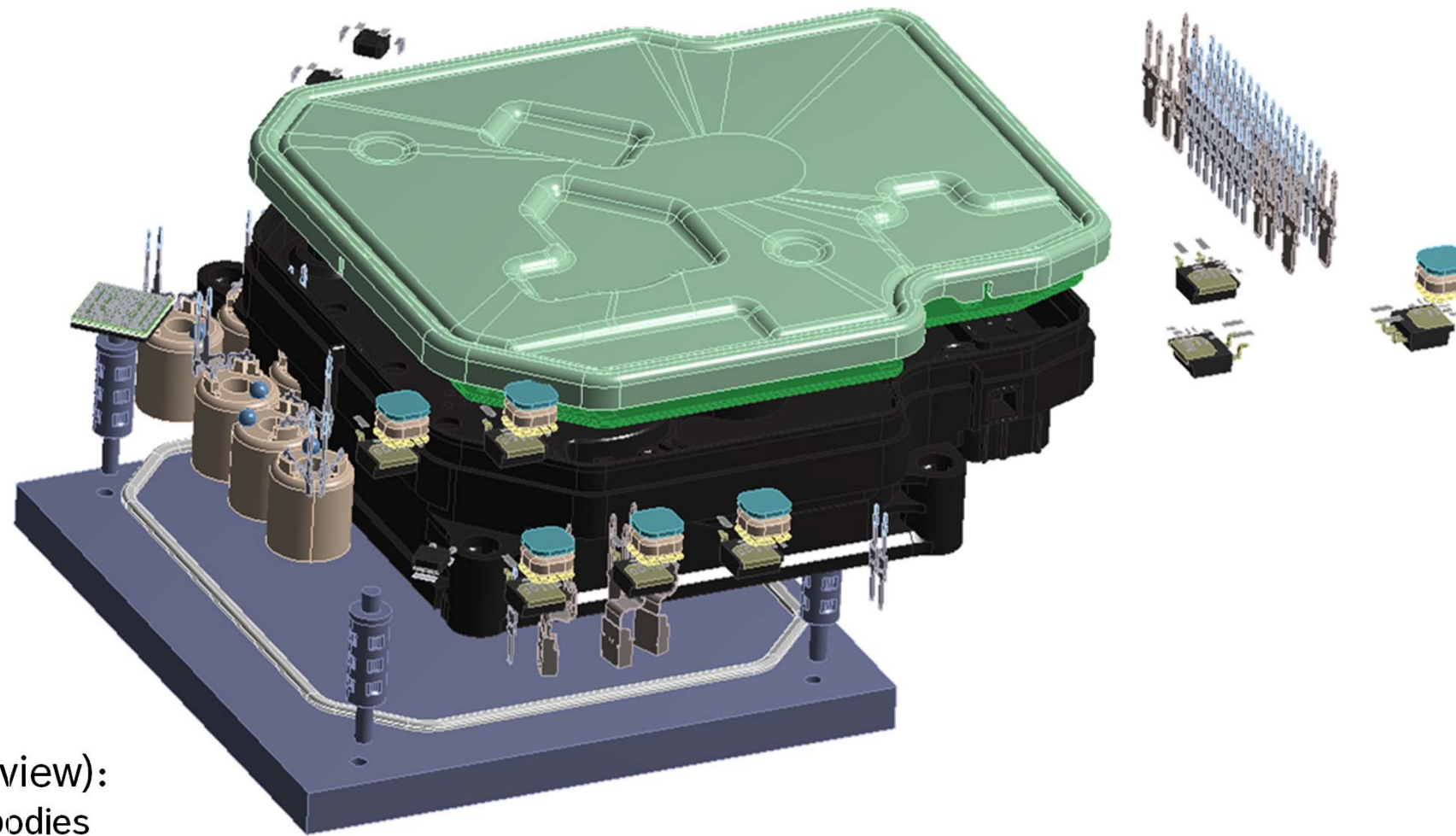
Postprocessing

dDOE

pDOE

Workflow

Run



ECU assembly

- ▶ Example (exploded view):
 - ▶ Assembly of 3000 bodies
 - ▶ Contact generation between components, PCB and housing parts

Virtual Assembly of ECUs

Load cases

Physics

Load Case

user1

Logout

i

?

Filter

Prepare PCB

Populate PCB

Assembly

Physics

Solve

Postprocessing

dDOE

pDOE

Workflow

Run

XML Details

Element	Value
analysis.analysisSystem	Transient Thermal
analysis.unitSystem	m

Filters

Name	Value
Physics	Thermal

Load Cases

- ▶ Prepared load cases can be chosen by user
- ▶ Load cases:
 - ▶ Thermal sources
 - ▶ Mechanical loads
 - ▶ Preloads
 - ▶ ...

Virtual Assembly of ECUs

DOE with discrete configurations

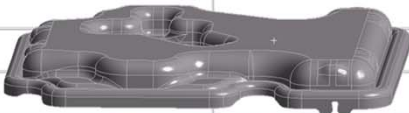


user1
[Logout](#)  

FilterPrepare PCBPopulate PCBAssemblyPhysicsSolvePostprocessingdDOEpDOEWorkflowRun

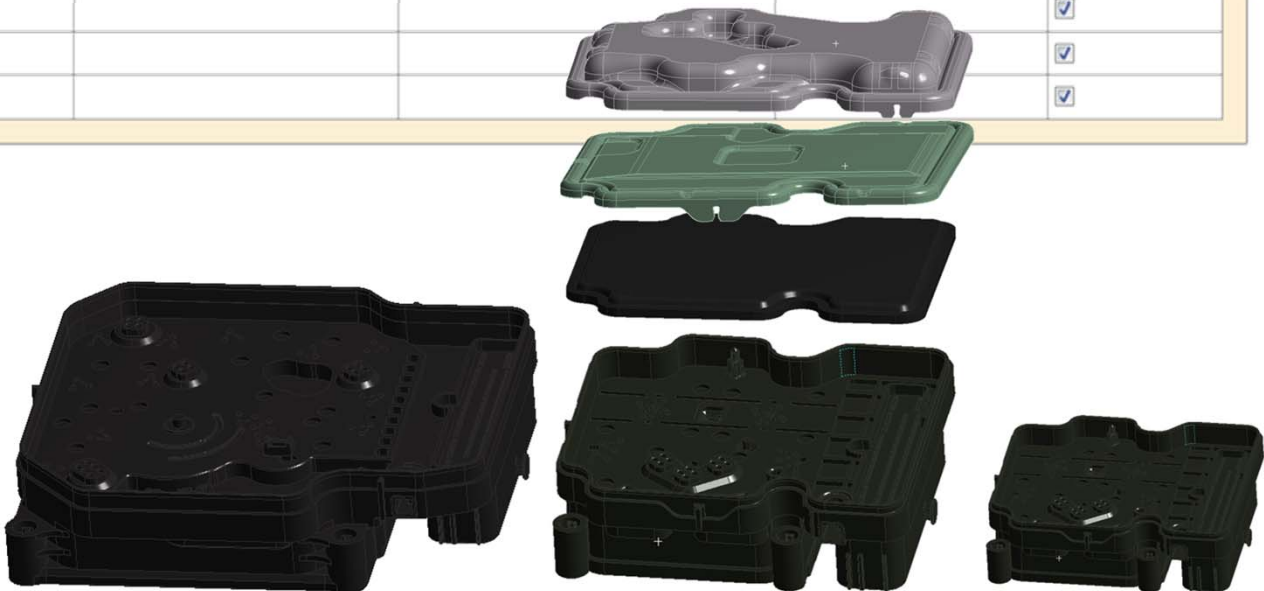
Parameter selection
☒PCB
☐Components
☐ECU Mechanics
☐Load Case

Sampling

Name	PCB	Components	ECU Mechanics	Load Case	Active
Design_1	ESP_Gen9_3_EV7110_B1				☒
Design_2	ESP_Gen9_3_EV7110_B1_refined2_cadfem				☒
Design_3	ESP_Gen9_3_EV7110_B1_refined_cadfem				☒
Design_4	ESP_Gen9_3_EV7110_B1_transformed_cadfem				☒
Design_5	ESP_Gen9_3_EV7140_C2				☒
Design_6	ESP_Gen9_3_EV7145_C1				☒

Discrete DOE

- ▶ Discrete configurations can be simulated and later compared
- ▶ Configurations:
 - ▶ Cover variants
 - ▶ PCB technology variations
 - ▶ Different component packages
 - ▶ Load variations
 - ▶ ...



Virtual Assembly of ECUs

DOE with continuous parameters



user1
Logout ⓘ ?

Filter

Prepare PCB

Populate PCB

Assembly

Physics

Solve

Postprocessing

dDOE

pDOE

Workflow

Run

pDOE Parameters

Active	Name	Value	Lower Bound	Upper Bound
☐	MyX	0.0	0.0	1.0
☐	MyWorkbenchParameter	1.0	0.1	2.0

Sampling

Sampling type

Plain Monte Carlo

Number of samples

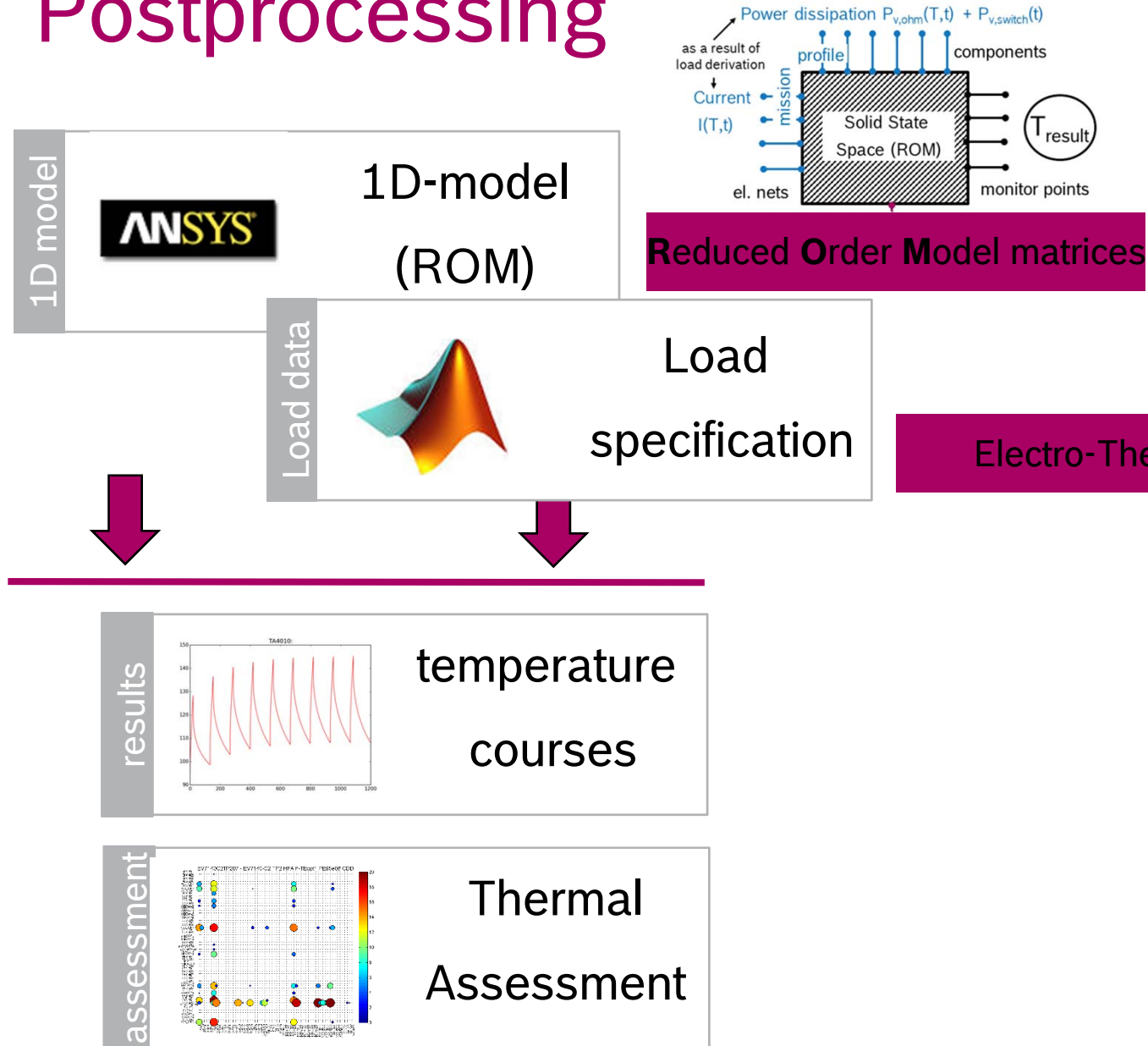
10

Parameter DOE

- ▶ Offers the parameters of the underlying Workbench projects
- ▶ Parameters:
 - ▶ CTE
 - ▶ Stiffness
 - ▶ Heat conductivity
 - ▶ ...

Virtual Assembly of ECUs

Postprocessing



EBS Thermal Assessment

Performs standardized Thermal Assessment for ESP Gen9.x & ESP Gen10

Go!



Setup of optiSLang project

- ▶ Simple optiSLang setup for the MATLAB-based calculation of temperature courses (and assessments) based on ANSYS-provided Reduced Order Model (ROM) matrices (MORinsideANSYS)
- ▶ Python-node to auto-generate Microsoft PowerPoint report
- ▶ Data Send node to send PowerPoint results + result zip-files by Email

Placeholders and Registered files

- ▶ Definition of placeholders to be provided by user interface

Virtual Assembly of ECUs

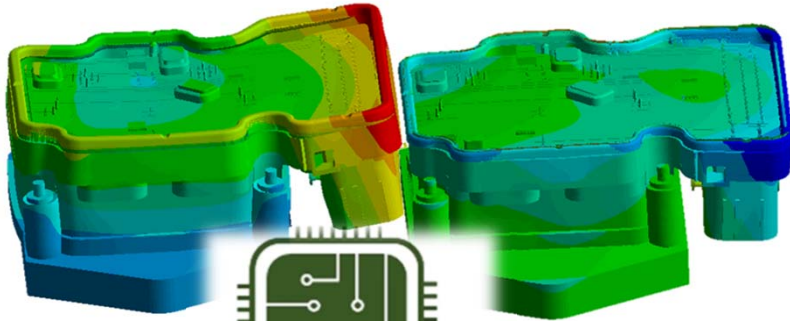
Submodels

Submodels

Upload an ECU model for submodel assessment. The result will be a design element reliability evaluation

Go!

FE calculation of thermo-mechanical ECU deformation



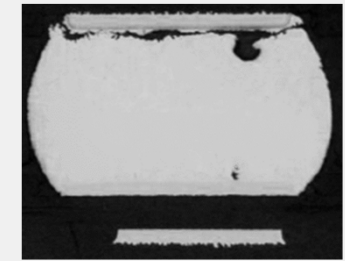
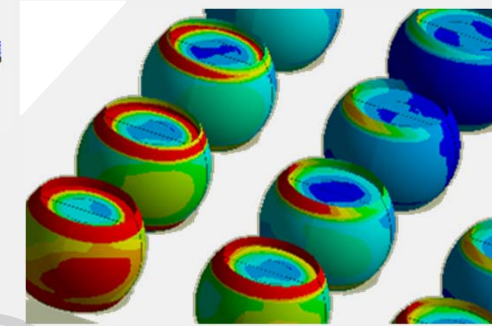
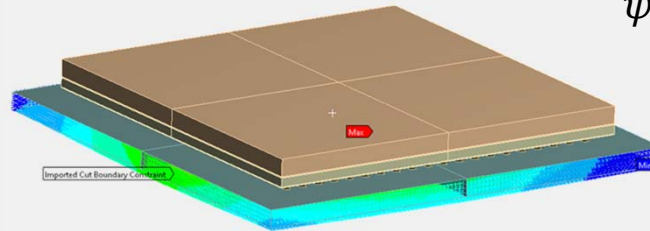
Virtual Assembly of ECUs

2nd level: calculation of damage inducing quantity on solder joint level:
rate-dependent non-linear kinematic hardening

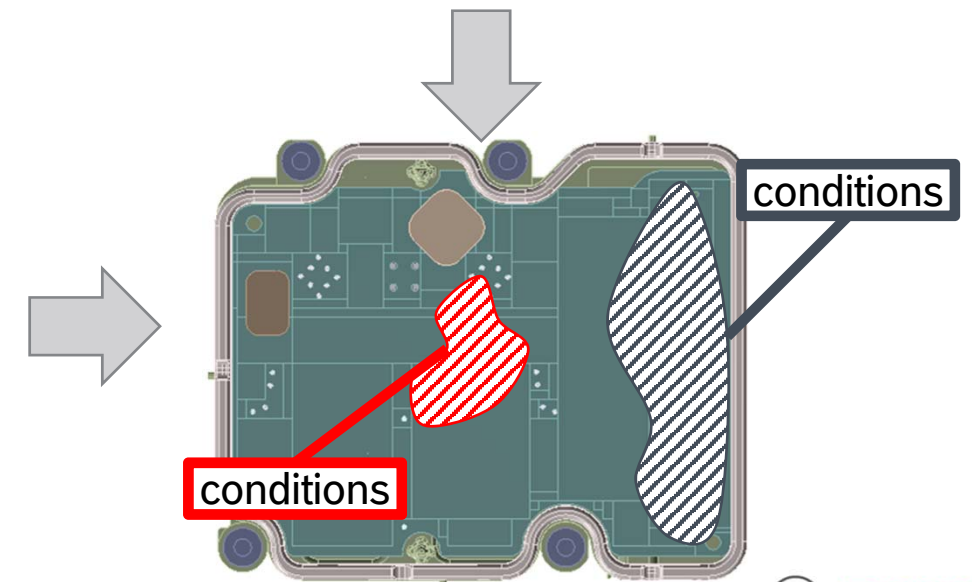
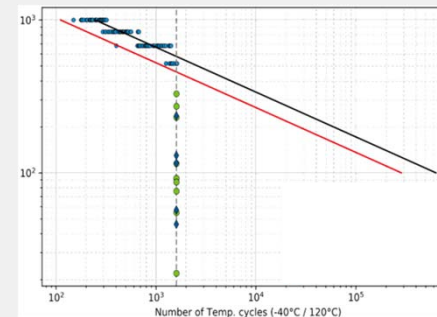
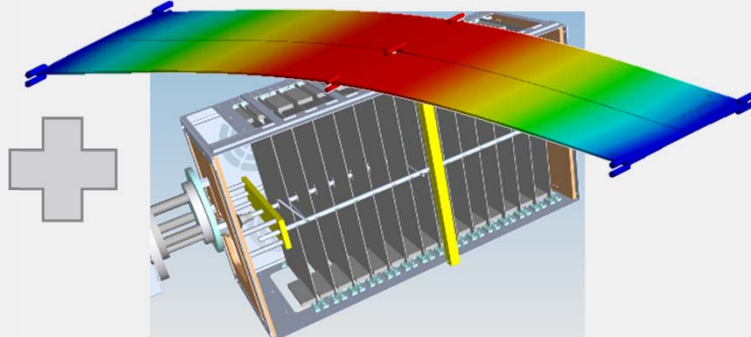
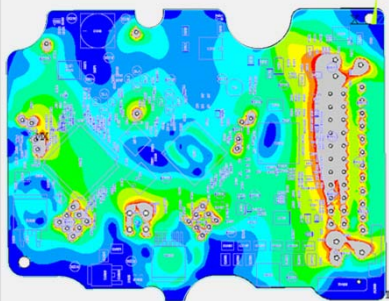
$$\psi = \psi(\epsilon^e, \epsilon^i, T, \dots)$$

+ continuum damage mechanics

$$\psi = \psi(\epsilon^e, \epsilon^i, T, \dots, D)$$



1st level: calculation of component specific damage inducing quantity on PCB level
+ evaluation with **experimentally obtained S-N curves**



Virtual Assembly of ECUs and more

This is only the beginning ...

► Process (SPM):

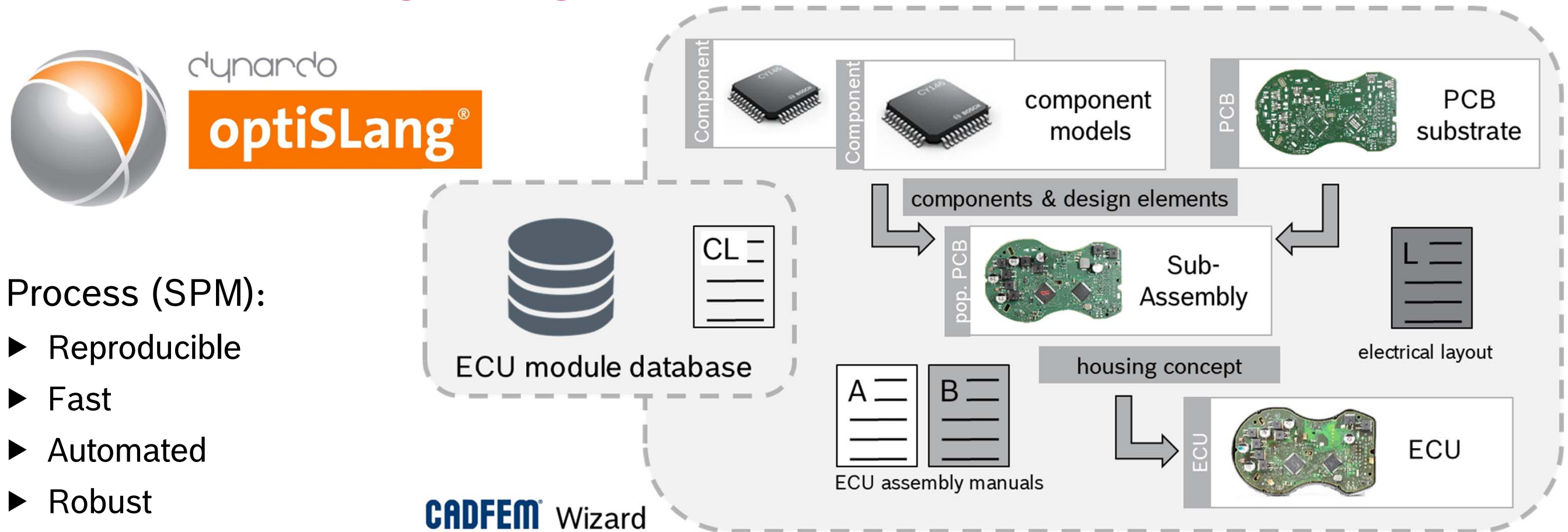
- Reproducible
- Fast
- Automated
- Robust

► Resources:

- Process owners for process definition and maintenance
- Large computational resources
- Efficient use of available licenses and resources

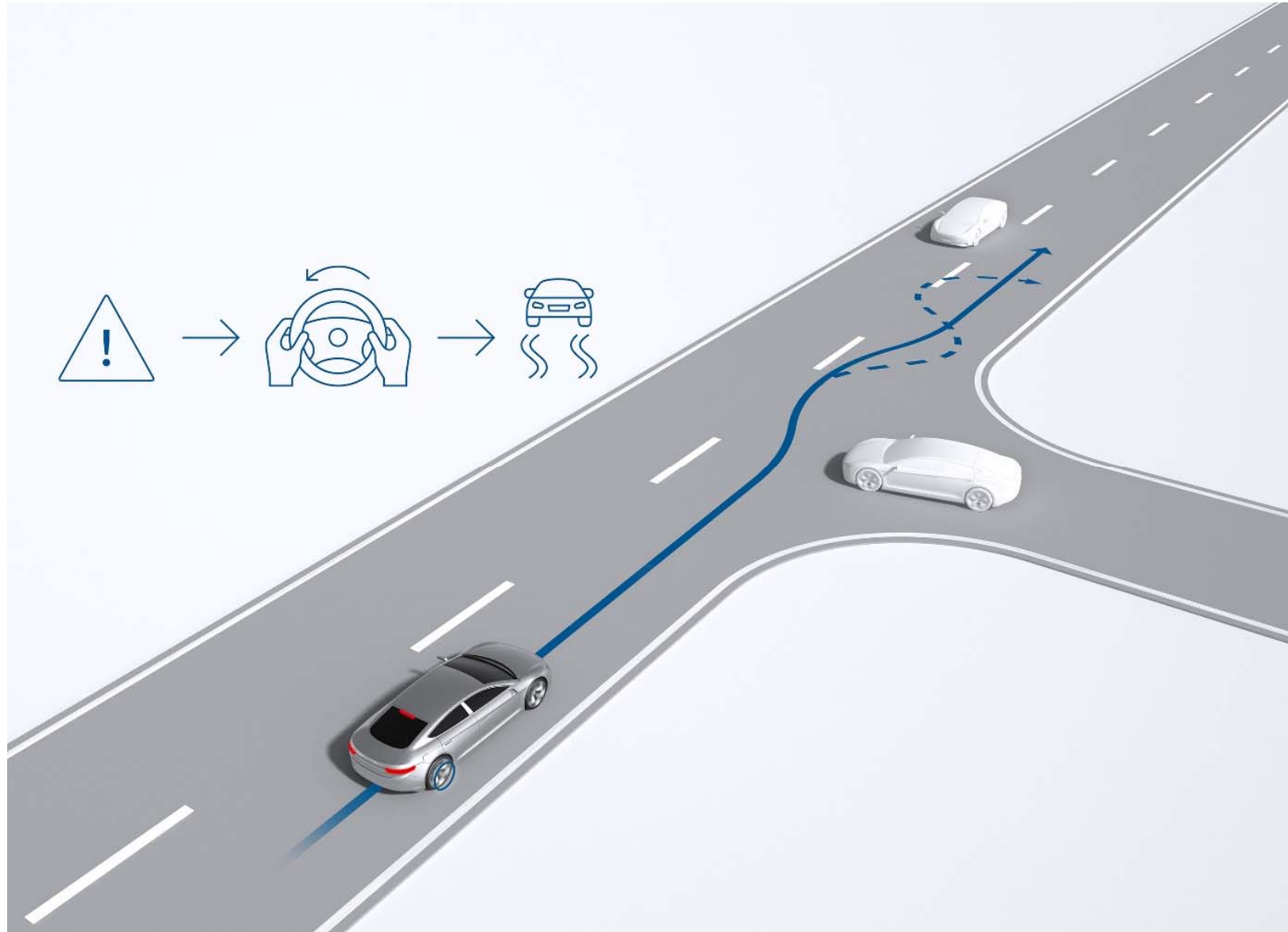
► Future:

- Meta-Models of scalable ECU architectures
- Sensitivity studies and Robust Design Optimization



Virtual Assembly of ECUs and more

Final remarks



Automated and efficient computational design assessment enables **design for reliability**

Vastly decreasing development times necessitate virtual design strategies and capacities

Future proof **simulation process (and data) management** concepts are implemented @BOSCH